



Product Change Notification

Change Notification #: 116708 - 00
Change Title: Intel® Server System R2308WTTYSR, PCN 116708-00, Product Design, Label, Outer box label stacking logo update, Hot-Swap Back Plane Firmware Update,
Date of Publication: January 14, 2019

Key Characteristics of the Change:

Product Design, Label

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material: *	January 30, 2019
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* Intel appreciates the customer's desire to receive the latest revision of products. However, Intel manages inventory on a first in first out (FIFO) basis at the MM# level. Subsequently, customer requests for a specific revision of material (below the MM#) will not be supported by Intel.

Description of Change to the Customer:

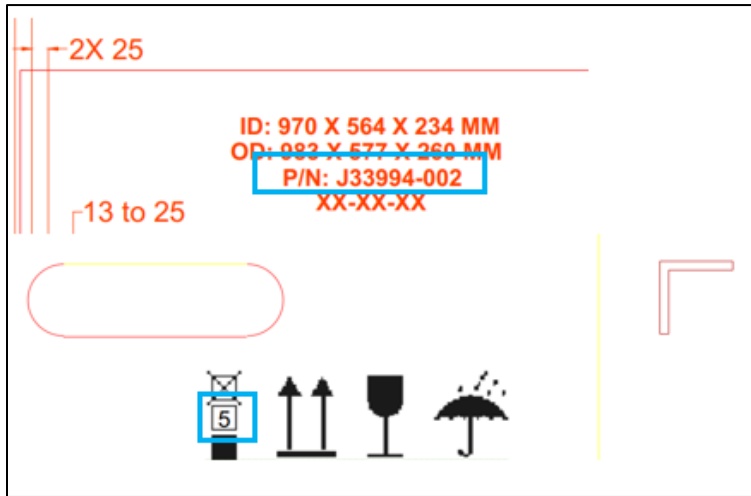
Intel is implementing the next changes to the Intel Server System listed on the products affected table.

1. Updated the outer box label logo.

The previous logo means that the maximum layers supported in a pallet are 7 in total, however only 6 layers as maximum can be supported. The P/N (Product Number) of the label is being updated for listed products as follow.

- I. Intel Server 1U Systems and 1U Chassis updates the P/N from J34109-001 to J34109-002.
- II. Intel Server 2U Systems and 2U Chassis updates the P/N from J34107-001 to J34107-002.

The Image below shows an example of the label logo P/N update.



2. Update the Hot-Swap Back Plane (HSBP) firmware from version 1.40 to 1.41.

Intel is updating the Hot-Swap Back Plane (HSBP) firmware from version 1.40 to 1.41. The firmware version 1.41 fixes a fault LED issue found on manufacturing.

3. PBA Riser change.

The PBA (Product Board Assembly) of the Server Riser 3 "A2UX8X4RISER" has implemented SMBus support. The system must have installed the Integrated Baseboard Management Controller (BMC) firmware to revision 01.51.11142 or newer version to enable the SMBUs communication from new Riser 3.

The Riser 3 "A2UX8X4RISER" that is integrated on the Intel server System R2308WTTYSR rolled up the TA from G97701-004 to G97701-005. For details of this change consult the PCN 116513 - 00.

Customer Impact of Change and Recommended Action:

Intel does not expect any other impact to customers from these changes, but encourages customers to understand the change and determine the impact on their applications. For that reason Intel recommends that the customer perform a standard level of evaluation. Customers can download and evaluate the latest BIOS/ME/Integrated BMC and FRUSDR release notes for more information at <http://www.intel.com/support>.

Products Affected / Intel Ordering Codes:

Product Code	MM#	Pre Change TA	Post Change TA
R2308WTTYSR	975760	J11493-014	J11493-015

PCN Revision History:

Date of Revision:

January 14, 2019

Revision Number:

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Reason:

Originally Published PCN



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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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